TOSHIBA CMOS Integrated Circuits Silicon Monolithic

TCA62724FMG

3-Channel Constant-Current LED Driver

The TCA62724FM is an optimal constant-current LED driver for RGB pixel LEDs.

The device supports 16 dimming states for each color in the RGB pixel LED setup, resulting in 4096 colors for carrying out illumination by internal PWM.

The Max forward current of the LED is set up using the external resistor.

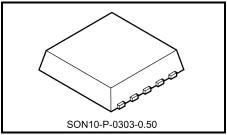
This IC is especially for driving back light white LEDs in LCD of PDA, Cellular Phone, or Handy Terminal Equipment.

The suffix (G) appended to the part number represents a Lead(Pb)-Free product.

Features

- Power supply voltage range
- Constant current range
- Low consumption current Supply current at operation (lout = 20mA/DC) Supply current at standby
 - For anode common LED
- I²C interface
- Package

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Weight: 0.018 g (typ.)

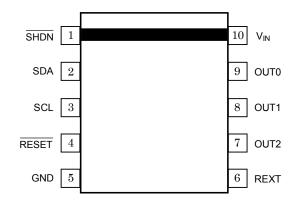
: VIN = 2.8 to 5.5 V

: 5 to 150 mA

: 700 µA(Max)

- : 1 µA(Max)
- : SON10-P-0303-0.50 Height : 0.8 mm (Typ.)

Pin Assignment (top view)

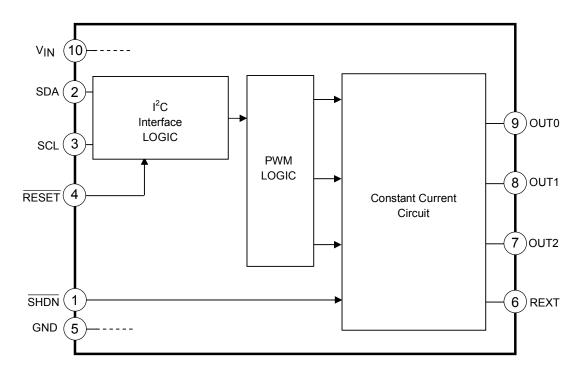


Terminal Description

Pin No.	Pin Name	Function
1	SHDN	IC input terminal enable. When the data is "L", power-saving mode applies; when the data is "H", the IC operates. Please do not open this terminal.
2	SDA	Serial data input / output terminal.
3	SCL	Serial clock input terminal.
4	RESET	Low active reset input terminal. When the data is "L", Data is reset applies; when the data is "H", the IC operates. Please do not open this terminal.
5	GND	GND terminal.
6	REXT	This is an output current setting resistor connect terminal. The output current does not flow when this terminal is opened. Excessive output current will destroy the IC if this terminal is connected to GND.
7	OUT2	
8	OUT1	Output terminal.
9	OUT0	
10	V _{IN}	2.8 V to 5.5 V supply voltage terminal.

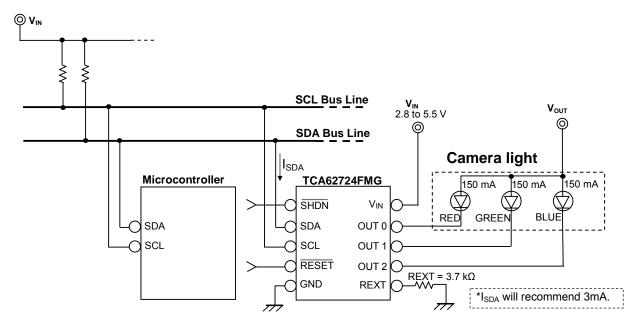
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Block Diagram



Example Applications : Cellular Phone

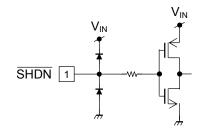
(Primary-color red, green and blue LEDs combine to emit good-quality white light for color reproducibility.)

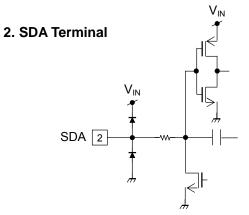


Application as Camera Light

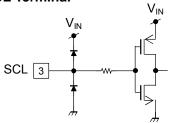
I/O Equivalent Pin Circuits

1. SHDN Terminal

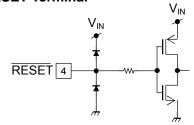




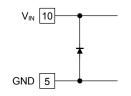
3. SCL Terminal



4. RESET Terminal



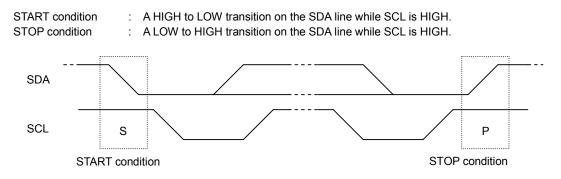
5. V_{IN},GND Terminal



I²C Interface

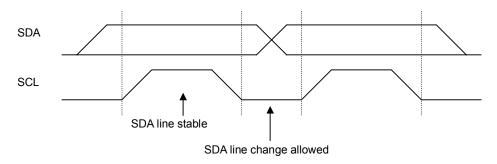
*DATA transfer format S Slave address 7 bits R/W A Sub-address 8 bits A DATA byte 8 bits A P

*START condition (S), STOP condition (P)



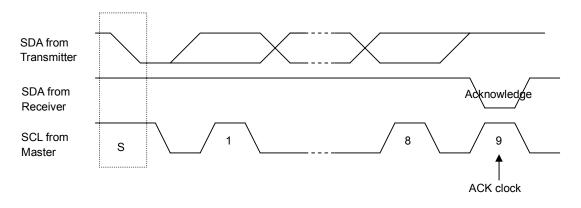
*DATA validity

The data on the SDA line must be stable during the HIGH period of the clock. The HIGH or LOW state of the data line can only change when the clock signal on the SCL line is LOW.



*Acknowledge (A)

The receiver is obliged to generate an Acknowledge after each byte has been received.



*Slave address

TCA62724FMG

10/1021241	NIC						
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
1	0	1	0	1	0	1	R/W

R/W: When this bit is set to "H", READ mode applies; when it is set to "L", WRITE mode applies.

*Sub-address

PWM0 (PWM Duty Data Setup of OUT0)

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0					
AI	0	0	0	0	0	0	1					

PWM1 (PWM Duty Data Setup of OUT1)

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Al	0	0	0	0	0	1	0
74	0	0	0	0	0	1	0

PWM2 (PWM Duty Data Setup of OUT2)

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
AI	0	0	0	0	0	1	1

ENABLE / SHDN (Data Setup of ENABLE / SHDN)

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
AI	0	0	0	0	1	0	0
		" •••••		<u> </u>			

Al: When this bit is set to "H", auto-increment is OFF; when it is set to "L", auto-increment is ON.

*DATA byte

PWM0, PWM1, and PWM2 DATA
$P(M/M \cap N)$ $D(t_1 \cap ATA) (0/15 to 15/15)$

	WM ON Duty DATA (0/15 to 15/15)										
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0				
	Don'	t use			PWM ON	Duty DATA					

(default ="0000")

Bit 3	Bit 2	Bit 1	Bit 0	
	DA	TA	1 0 1 0 1 0 1 0 1 0 1 0 1 0 1 0 1 0 1	PWM ON Duty
1	1	1	1	15/15
1	1	1	0	14/15
1	1	0	1	13/15
1	1	0	0	12/15
1	0	1	1	11/15
1	0	1	0	10/15
1	0	0	1	9/15
1	0	0	0	8/15
0	1	1	1	7/15
0	1	1	0	6/15
0	1	0	1	5/15
0	1	0	0	4/15
0	0	1	1	3/15
0	0	1	0	2/15
0	0	0	1	1/15
0	0	0	0	0/15

ENABLE / SHDN DATA

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
	Don'	t use		х	х	ENABLE	SHDN

(default = "00000000")

ENABLE DATA H

L

L

: Output blinks at PWM0, PWM1, and PWM2 rate

: Output is OFF

SHDN data H

: Output blinks at PWM0, PWM1, and PWM2 rate

: Power-saving mode

*WRITE mode

Auto	Auto-increment OFF											
S	Slave Address	R/W (0)	A	Sub- address	А	DATA	A	Sub- address	A	DATA		Ρ

Auto-increment ON

		••								
S	Slave Address	R/W (0)	A	Sub- address	A	DATA	A	DATA	A	 Ρ

The data of the immediately following Sub-address can be written in.

*READ mode

S	Slave Address	R/W (1)	А	First Byte	A	Second Byte	Ρ	
---	------------------	------------	---	------------	---	-------------	---	--

First byte (ENABLE / SHDN DATA and PWM2 DATA)

l	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
F	х	х	ENABLE	SHDN		PWM2	DATA	

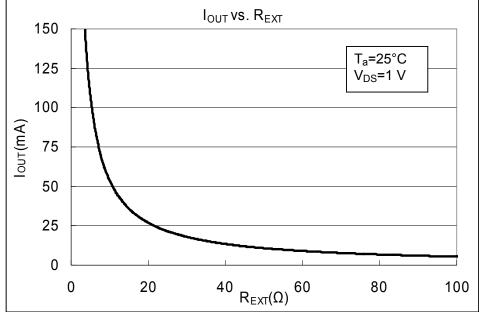
Second byte (PWM1 DATA and PWM0 DATA)

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
PWM1 DATA					PWM0) data	

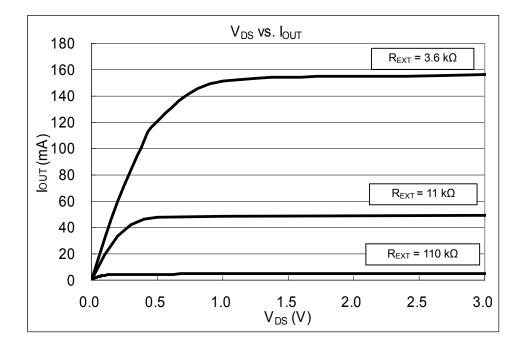
Setting of Output Current (Reference Data)

The output current is set by the resistance connected between terminal R_{EXT} and GND. The output current can be set according to the following expression.

$$I_{OUT}$$
 (mA) = $\frac{1.17 (V)}{R_{EXT} (k\Omega)} \times 460$



Output Voltage – Output Current (Reference Data)



Note1: These application examples are provided for reference only. Thorough evaluation and testing should be implemented when designing your application's mass production design.

Absolute Maximum Ratings (T_a = 25°C)

Characteristic	Symbol	Ratings	Unit
Supply voltage	V _{IN}	-0.3 ~ +6.0	V
Output voltage	V _{OUT}	-0.3 ~ +6.0	V
Input voltage (SDA/SCL/ <u>SHDN/RESET</u> Terminal)	Vin	–0.3 ~ V _{IN} +0.3 (Note2)	mA
Denne dia inglia	Б	0.36 (free air)	w
Power dissipation	PD	0.79(on PCB)*	v v
	_	340 (free air)	0000
Thermal resistance	R _{th (j-a)}	158 (on PCB) (Note3)	°C/W
Operating temperature	T _{opr}	-40 ~ +85	°C
Storage temperature	T _{stg}	-55 ~ +150	°C
Maximum junction temperature	Tj	150	°C

Note2: However, do not exceed 6V.

Note3: Subtract 6.3 mW / degree from the absolute maximum rating value about a degree if the operation temperature

exceeds 25°C when the device is mounted on a PCB. (PCB : 40mm × 40mm × 1.6mm, Cu = 40%, FR4)

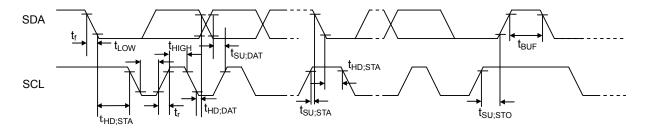
Recommended Operating Condition

Characteristic	Symbol	Condition	Min	Тур.	Мах	Unit
Supply voltage	V _{IN}	-	2.8	3.6	5.5	V
Constant current output	l _{оит}	OUT0 to OUT2	5	-	150	mA/ch
REXT	R _{EXT}	-	3.7	-	109	kΩ

Characteristic		Symbol	Condition	Min	Тур	Max	Unit
Supply voltage		V _{IN}	-	2.8	3.6	5.5	V
Supply current (IC operation)		I _{IN} (On)	R_{EXT} = 27.6 k Ω , V_{IN} = 3.6 V	-	-	700	μA
Supply current	(IC standby)	I _{IN} (Off)	SHDN = L	-	-	1.0	μA
	High level	V _{IH}	SDA, SCL, SHDN, RESET	0.7V _{IN}	-	V _{IN} +0.15V	V
Input voltage	Low level	VIL	SDA, SCL, SHDN, RESET	-0.15	-	0.3V _{IN}	
High level		IIH	SCL, SHDN, RESET	-1.0	-	1.0	A
Input current	Low level	١ _{١L}	SCL, SHDN, RESET	-1.0	-	1.0	μA
Gain		GAIN	I _{OUT} /I _{REXT} , R _{EXT} =11kΩ	359	460	560	
REXT terminal	voltage	V _{REXT}	V _{IN} =3.6V, R _{EXT} =11kΩ	1.09	1.17	1.25	V
Output leakage	current	l _{oz}	SHDN="L", V _{OUT} =5.5V	-	-	0.1	μΑ
Constant current accuracy between bits		dl _{out}	V _{IN} = 3.6 V, R _{EXT} = 11 kΩ	-	±1	±7.5	%
PWM frequency		f _{PWM}	-	-	3.0	-	kHz
Time from SHDN release to start of operation		t _{RE}	-	-	-	5	ms

Characteristics of the SDA and SCL Bus Lines for I²C-bus Devices

Characteristic	Symbol	Standar	d Mode	Unit
Characteristic	Symbol	Min	Max	
SCL clock frequency	f _{SCL}	0	100	kHz
Bus free time between STOP and START condition	t _{BUF}	4.7	-	μs
Hold time (repeated) START condition	t _{HD;STA}	4.0	-	μs
Setup time for repeated START condition	t _{su;sta}	4.7	-	μs
Setup time for STOP condition	t _{su;sto}	4.0	-	μs
Data hold time	t _{HD;DAT}	0	-	ns
Data setup time	t _{SU;DAT}	250	-	ns
LOW period of the SCL clock	t _{LOW}	4.7	-	μs
HIGH period of the SCL clock	t _{HIGH}	4.0	-	μs
Rise time of both SDA and SCL signals	t _f	-	1000	ns
Fall time of both SDA and SCL signals	tr	-	300	ns



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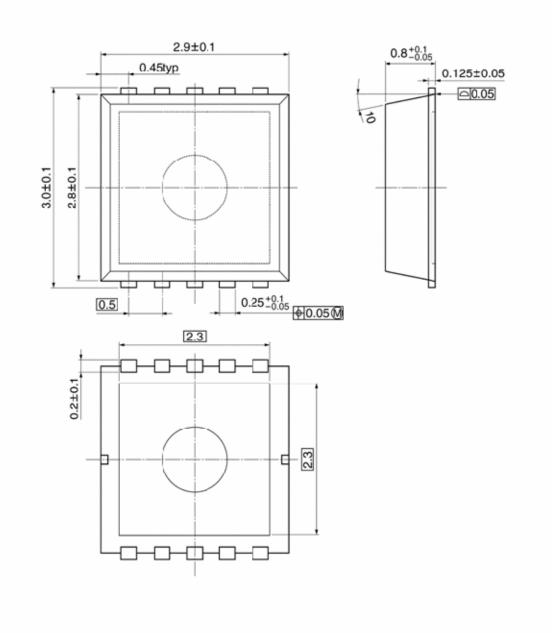
Marking

		Week 1-26
С	07	C 0 7
Q	A 1	Q A 1
		Week 27-53
C01 Q	: Product number : Monthly and weekly	code C 0 7
A1	: Lot code	Q A 1

Package Dimensions

SON10-P-0303-0.50

Unit: mm



Weight: 0.018 g (typ.)

Notes on Contents

1. Block Diagrams

Some of the functional blocks, circuits, or constants in the block diagram may be omitted or simplified for explanatory purposes.

2. Equivalent Circuits

The equivalent circuit diagrams may be simplified or some parts of them may be omitted for explanatory purposes.

3. Timing Charts

Timing charts may be simplified for explanatory purposes.

4. Application Circuits

The application circuits shown in this document are provided for reference purposes only. Thorough evaluation is required, especially at the mass production design stage. Toshiba does not grant any license to any industrial property rights by providing these examples of application circuits.

5. Test Circuits

Components in the test circuits are used only to obtain and confirm the device characteristics. These components and circuits are not guaranteed to prevent malfunction or failure from occurring in the application equipment.

IC Usage Considerations

Notes on Handling of ICs

- The absolute maximum ratings of a semiconductor device are a set of ratings that must not be exceeded, even for a moment. Do not exceed any of these ratings. Exceeding the rating(s) may cause the device breakdown, damage or deterioration, and may result injury by explosion or combustion.
- (2) Use an appropriate power supply fuse to ensure that a large current does not continuously flow in case of over current and/or IC failure. The IC will fully break down when used under conditions that exceed its absolute maximum ratings, when the wiring is routed improperly or when an abnormal pulse noise occurs from the wiring or load, causing a large current to continuously flow and the breakdown can lead smoke or ignition. To minimize the effects of the flow of a large current in case of breakdown, appropriate settings, such as fuse capacity, fusing time and insertion circuit location, are required.
- (3) If your design includes an inductive load such as a motor coil, incorporate a protection circuit into the design to prevent device malfunction or breakdown caused by the current resulting from the inrush current at power ON or the negative current resulting from the back electromotive force at power OFF. IC breakdown may cause injury, smoke or ignition.

Use a stable power supply with ICs with built-in protection functions. If the power supply is unstable, the protection function may not operate, causing IC breakdown. IC breakdown may cause injury, smoke or ignition.

(4) Do not insert devices in the wrong orientation or incorrectly. Make sure that the positive and negative terminals of power supplies are connected properly. Otherwise, the current or power consumption may exceed the absolute maximum rating, and exceeding the rating(s) may cause the device breakdown, damage or deterioration, and may result injury by explosion or combustion.

In addition, do not use any device that is applied the current with inserting in the wrong orientation or incorrectly even just one time.

(5) Carefully select external components (such as inputs and negative feedback capacitors) and load components (such as speakers), for example, power amp and regulator. If there is a large amount of leakage current such as input or negative feedback condenser, the IC output DC voltage will increase. If this output voltage is connected to a speaker with low input withstand voltage, overcurrent or IC failure can cause smoke or ignition. (The over current can cause smoke or ignition from the IC itself.) In particular, please pay attention when using a Bridge Tied

Load (BTL) connection type IC that inputs output DC voltage to a speaker directly.

Points to Remember on Handling of ICs

(1) Heat Radiation Design

In using an IC with large current flow such as power amp, regulator or driver, please design the device so that heat is appropriately radiated, not to exceed the specified junction temperature (Tj) at any time and condition. These ICs generate heat even during normal use. An inadequate IC heat radiation design can lead to decrease in IC life, deterioration of IC characteristics or IC breakdown. In addition, please design the device taking into considerate the effect of IC heat radiation with peripheral components.

(2) Back-EMF

When a motor rotates in the reverse direction, stops or slows down abruptly, a current flow back to the motor's power supply due to the effect of back-EMF. If the current sink capability of the power supply is small, the device's motor power supply and output pins might be exposed to conditions beyond absolute maximum ratings. To avoid this problem, take the effect of back-EMF into consideration in system design.

About solderability, following conditions were confirmed					
Solderability					
 (1) Use of Sn-37Pb solder Bath solder bath temperature = 230°C dipping time = 5 seconds the number of times = once use of R-type flux 					
 (2) Use of Sn-3.0Ag-0.5Cu solder Bath solder bath temperature = 245°C dipping time = 5 seconds the number of times = once use of R-type flux 					

RESTRICTIONS ON PRODUCT USE

Handbook" etc. 021023 A

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